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[Continued on next page]

(54) Title: ELECTROPLATING AQUEOUS SOLUTION AND METHOD OF MAKING AND USING SAME

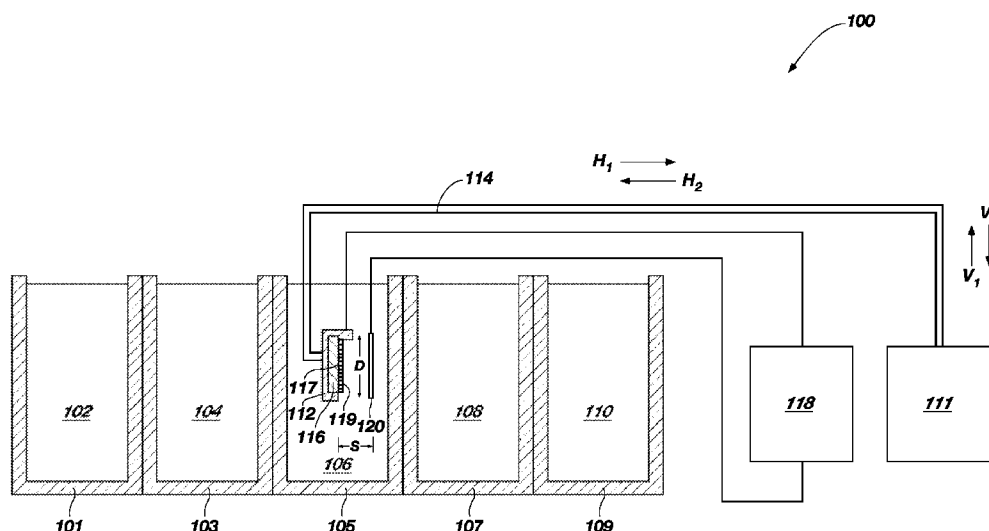


FIG. 1A

(57) Abstract: In one embodiment of the invention, an electroplating aqueous solution is disclosed. The electroplating aqueous solution includes at least two acids, copper, at least one accelerator agent, and at least two suppressor agents. The at least one accelerator agent provides an acceleration strength of at least about 2.0 and the at least two suppressor agents, collectively, provide a suppression strength of at least about 5.0. Methods of making and using such an electroplating aqueous solution are also disclosed.

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